

Pb ead-free Gree

DUAL N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Available in Lead Free/RoHS Compliant Version (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability
- "Green" Device (Notes 5 and 6)

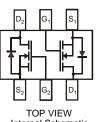
Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic. "Green" Molding Compound (Note 6). UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating) Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)

SOT-363



TOP VIEW



Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristi	c	Symbol	BSS138DW	Units		
Drain-Source Voltage		V _{DSS}	50	V		
Drain-Gate Voltage (Note 3)		V _{DGR}	50	V		
Gate-Source Voltage	Continuous	V _{GSS}	±20	V		
Drain Current (Note 1)	Continuous	ID	200	mA		

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	BSS138DW	Units
Total Power Dissipation (Note 1)	PD	200	mW
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 2)						
Drain-Source Breakdown Voltage	BV _{DSS}	50	75	_	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_		0.5	μA	$V_{DS} = 50V, V_{GS} = 0V$
Gate-Body Leakage	I _{GSS}	_		±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage	V _{GS(th)}	0.5	1.2	1.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	1.4	3.5	Ω	V _{GS} = 10V, I _D = 0.22A
Forward Transconductance	g fs	100	_	_	mS	V _{DS} =25V, I _D = 0.2A, f = 1.0KHz
DYNAMIC CHARACTERISTICS						
Input Capacitance	Ciss	_		50	pF	
Output Capacitance	Coss	_	_	25	pF	$V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz$
Reverse Transfer Capacitance	Crss	_		8.0	pF	
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{D(ON)}	_		20	ns	$V_{DD} = 30V, I_D = 0.2A,$
Turn-Off Delay Time	t _{D(OFF)}			20	ns	$R_{GEN} = 50\Omega$

Notes: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

2. Short duration pulse test used to minimize self-heating effect.

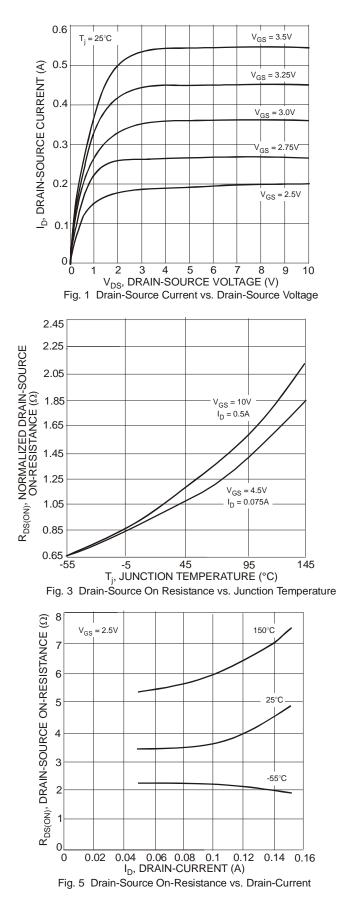
3. $R_{GS} \leq 20 K\Omega$.

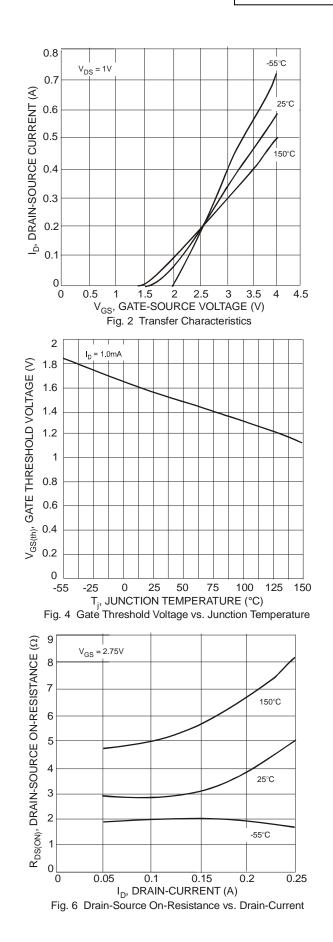
No purposefully added lead.

5. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

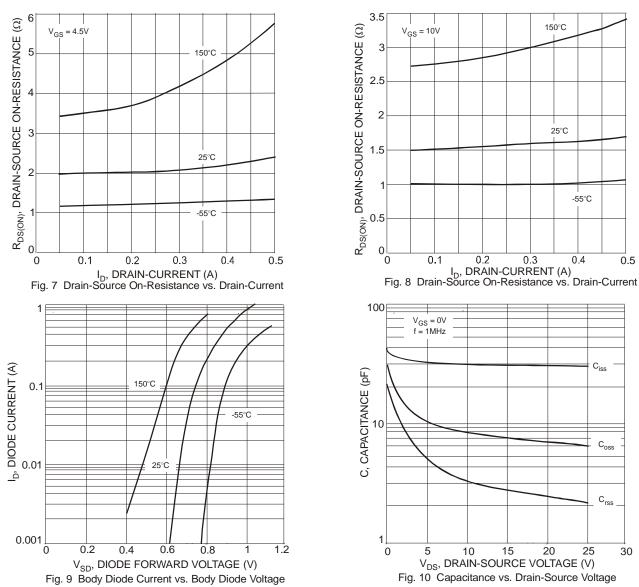
 Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.









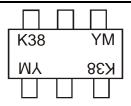


Ordering Information (Note 7)

Part Number	Case	Packaging
BSS138DW-7-F	SOT-363	3000/Tape & Reel

Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



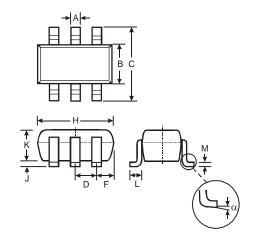
K38 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: N = 2002) M = Month (ex: 9 = September)

Date Code Key

Date Code Key															
Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	J	K	L	М	Ν	Р	R	S	Т	U	V	W	Х	Y	Z
Month	Jan	Fe	b	Mar	Apr	May	Ju	n	Jul	Aug	Sep	Oct	N	lov	Dec
Code	1	2		3	4	5	6		7	8	9	0		N	D

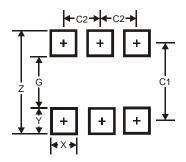


Package Outline Dimensions



SOT-363							
Dim	Min	Max					
Α	0.10	0.30					
В	1.15 1.35						
С	2.00 2.20						
D	0.65	Тур					
F	0.40 0.45						
Н	1.80 2.20						
J	0 0.10						
κ	0.90 1.00						
L	L 0.25 0.40						
М	M 0.10 0.22						
α	0°	8°					
All Dimensions in mm							

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



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